

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	"6780673".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 11:17
S2	5	("5279711"   "6261883"   "6274391"   "6281111"   "6521530").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/11 14:47
S3	68	(package near substrate or wiring near substrate or pcb or pwb) same (via or viahole or feedthrough or feedthru) near10 (electrode or pad or terminal) same (surface or outside or top or exterior or above or pad or contact or electrode) near3 (ground) same (chip or die or ic)	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/11 14:56
S4	154	(package near substrate or wiring near substrate or pcb or pwb) same (electrode or pad or terminal) near5 (solder near ball or bga) near5 (chip or ic or die) and (surface or outside or top or exterior) near5 (metal or metallization or metallized or metallizing or metallic)	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/11 16:46
S5	1	("20020189849").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/11 15:46
S6	11	("4003621"   "4249302"   "4932883"   "5071359"   "5245751"   "5427535"   "5828226"   "6264476"   "6663399"   "6712620"   "6722893").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/11 15:47
S7	33	(package near substrate or wiring near substrate or pcb or pwb) same (signal or contact or wiring) near (pad or electrode or terminal) near6 (surface or outside or top or exterior or upon or outer) near6 (ground)	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/11 16:57
S8	50	(package near substrate or wiring near substrate or pcb or pwb) near10 (surface or top or upper or outside or outer or exterior) near8 (metal or metallization or metallized or metallizing or metallic) near10 (channel or groove or grooved or trench or trenched or spacer or spaces)	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/12 08:47
S9	622	(package near substrate or wiring near substrate or pcb or pwb) same (ground) near2 (plane or pad or terminal or electrode or contact) near6 (top or above or upper or surface or outside or outer or overlying)	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/12 08:48
S10	144	(package near substrate or wiring near substrate or pcb or pwb) same (ground) near2 (plane or pad or terminal or electrode or contact) near6 (top or above or upper or surface or outside or outer or overlying) and (bga or solder near ball)	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/12 08:48
S11	1	("6479758").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/12 08:59
S12	4	("6225702"   "6384476"   "6388207"   "6479758").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/12 09:01
S13	4	("20020113319"   "20030094631"   "20030122213"   "20030132529").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/12 09:03
S16	318	257/691.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 12:44
S17	211	257/698.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 13:07

S18	270	257/700.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 13:27
S19	87	257/730.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 13:37
S20	693	257/778.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 13:38
S21	389	257/778.ccor. and (solder near ball or bga or ball near grid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 14:17
S22	119	257/779.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 14:55
S23	326	257/786.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:03
S25	19	(US-20020121689-\$ or US-20020132463-\$ or US-20020180027-\$ or US-20030122213-\$ or US-20030146510-\$ or US-20050017345-\$).did. or (US-4937472-\$ or US-5188280-\$ or US-6108212-\$ or US-6154370-\$ or US-6388207-\$ or US-6479949-\$ or US-6521530-\$ or US-6610934-\$ or US-6707145-\$ or US-6740965-\$ or US-6800947-\$ or US-6828669-\$ or US-6861740-\$).did.	US-PGPUB; USPAT	OR	ON	2005/07/18 16:09
S26	2	"6261883".pn. "6274391".pn.	US-PGPUB; USPAT	OR	ON	2005/07/18 16:29
S27	18	(bga or ball near grid or solder near ball) and (solder near mask) near4 oxide	US-PGPUB; USPAT	OR	ON	2005/07/18 16:36